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(54) Title (EN): ADHESIVE FOR MOUNTING ELECTRONIC COMPONENT AND ADHESIVE FILM FOR MOUNTING FLIP CHIP

(54) Title (FR): ADHÉSIF POUR MONTAGE DE COMPOSANT ÉLECTRONIQUE, ET FILM ADHÉSIF POUR MONTAGE DE PUCE RETOURNÉE

(54) Title (JA): 電子部品実装用接着剤及びフリップチップ実装用接着フィルム

(57) Abstract:

(EN): The purpose of the present invention is to provide an electronic component mounting adhesive that can achieve sufficient solder bonding within a short mounting time while suppressing solder flow, that suppresses voids, and that has excellent reflow resistance. Another purpose of the present invention is to provide a flip chip mounting adhesive film that includes the electronic component mounting adhesive. The present invention is an electronic component mounting adhesive that contains: an acryl polymer that has a double bond equivalence of 1-5 meq/g and that has a methacryloyl group as a side chain; a polyfunctional methacrylate compound that has three or more functional groups; and a radical polymerization initiator.

(FR): L'invention a pour objectif de fournir un adhésif pour montage de composant électronique qui permet de réaliser un joint à brasure tendre suffisant tout en évitant un écoulement de brasure en un temps de montage court, qui supprime les vides, et qui présente une excellente résistance à la refusion. En outre, l'invention a pour objectif de fournir un film adhésif pour montage de puce retournée qui contient cet adhésif pour montage de composant électronique. L'adhésif pour montage de composant électronique de l'invention comprend : un polymère acrylique d'équivalent de double liaison compris entre 1 et 5méq/g qui possède un (méth)acryloyle sur une chaîne latérale ; un composé de (méth)acrylate multifonction de trois fonctions ou plus ; et un initiateur de polymérisation radicalaire.

(JA): 本発明は、短い実装時間の中で半田流れを抑えつつ充分に半田接合でき、ボイドを抑制し、耐リフロー性にも優れた電子部品実装用接着剤を提供することを目的とする。また、本発明は、該電子部品実装用接着剤を含むフリップチップ実装用接着フィルムを提供することを目的とする。本発明は、側鎖に(メタ)アクリロイル基を有する二重結合当量１～５ｍｅｑ／ｇのアクリルポリマーと、３官能以上の多官能(メタ)アクリレート化合物と、ラジカル重合開始剤とを含有する電子部品実装用接着剤である。

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